

P-Channel Enhancement Mode Power MOSFET

Description

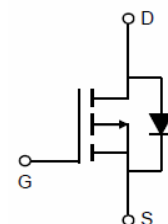
The HM45P02Q uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

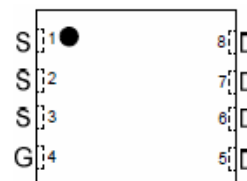
- $V_{DS} = -20V, I_D = -45A$
 $R_{DS(ON)} < 7m\Omega @ V_{GS} = -4.5V$
 $R_{DS(ON)} < 9m\Omega @ V_{GS} = -2.5V$
 $R_{DS(ON)} < 12m\Omega @ V_{GS} = -1.8V$
- High density cell design for ultra low R_{dson}
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

Application

- Load switch
- Battery protection



Schematic diagram



Pin Assignment



DFN 3.3x3.3 EP top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
HM45P02Q	HM45P02Q	DFN 3.3x3.3 EP	-	-	-

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	-45	A
Drain Current-Continuous($T_C = 100^\circ C$)	$I_D(100^\circ C)$	-35	A
Pulsed Drain Current	I_{DM}	-200	A
Maximum Power Dissipation	P_D	80	W
Derating factor		0.64	W/ $^\circ C$
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{\theta JC}$	1.6	$^\circ C/W$
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Electrical Characteristics ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-20	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-16V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.6	-1.0	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=-4.5V, I_D=-20A$	-	5.8	7	m Ω
		$V_{GS}=-2.5V, I_D=-20A$	-	7.2	9	
		$V_{GS}=-1.8V, I_D=-20A$	-	9	12	
Forward Transconductance	g_{FS}	$V_{DS}=-5V, I_D=-20A$	80	-	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C_{iss}	$V_{DS}=-10V, V_{GS}=0V,$ $F=1.0\text{MHz}$	-	3500	-	PF
Output Capacitance	C_{oss}		-	577	-	PF
Reverse Transfer Capacitance	C_{rss}		-	445	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-10V, R_{GEN}=3\Omega$ $V_{GS}=-4.5V, R_L=0.5\Omega$	-	18	-	nS
Turn-on Rise Time	t_r		-	42	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	85	-	nS
Turn-Off Fall Time	t_f		-	23	-	nS
Total Gate Charge	Q_g	$V_{DS}=-10V, I_D=-20A,$ $V_{GS}=-4.5V$	-	55	-	nC
Gate-Source Charge	Q_{gs}		-	10	-	nC
Gate-Drain Charge	Q_{gd}		-	15	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	$V_{GS}=0V, I_S=-20A$	-	-	-1.2	V
Diode Forward Current (Note 2)	I_S		-	-	-45	A
Reverse Recovery Time	t_{rr}	$T_J = 25^{\circ}\text{C}, I_F = -10A$ $di/dt = 100A/\mu s$ (Note 3)	-	47	-	nS
Reverse Recovery Charge	Q_{rr}		-	53	-	nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics (Curves)

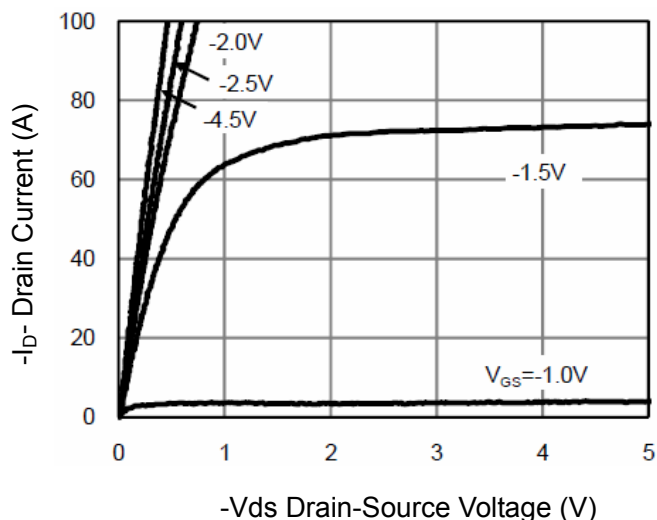


Figure 1 Output Characteristics

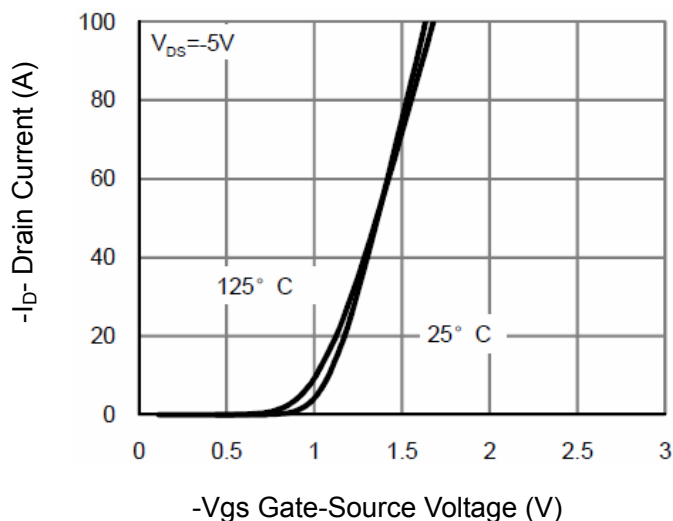


Figure 2 Transfer Characteristics

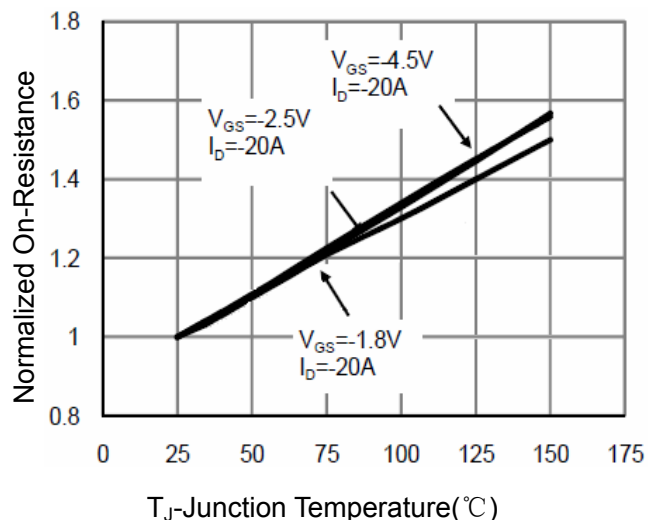


Figure 4 Rdson-Junction Temperature

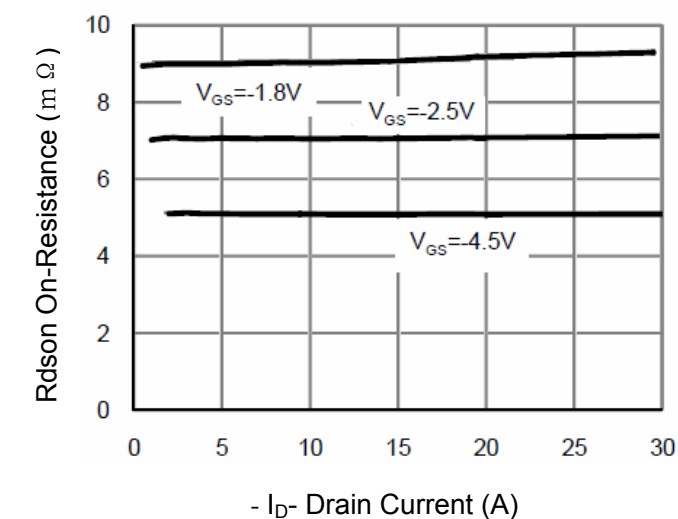


Figure 3 Rdson- Drain Current

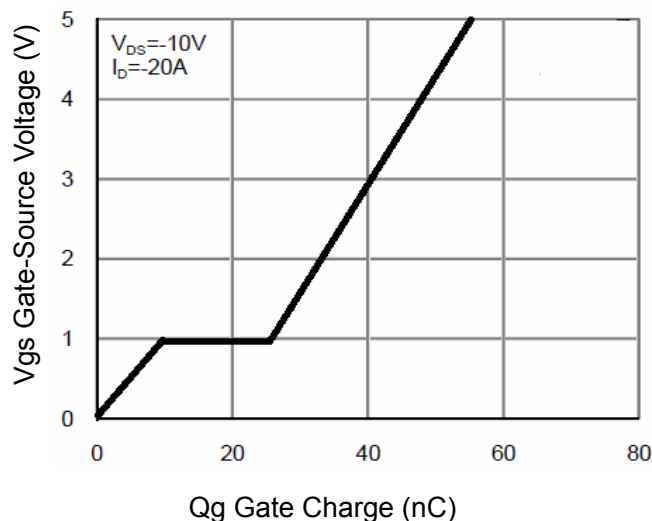


Figure 5 Gate Charge

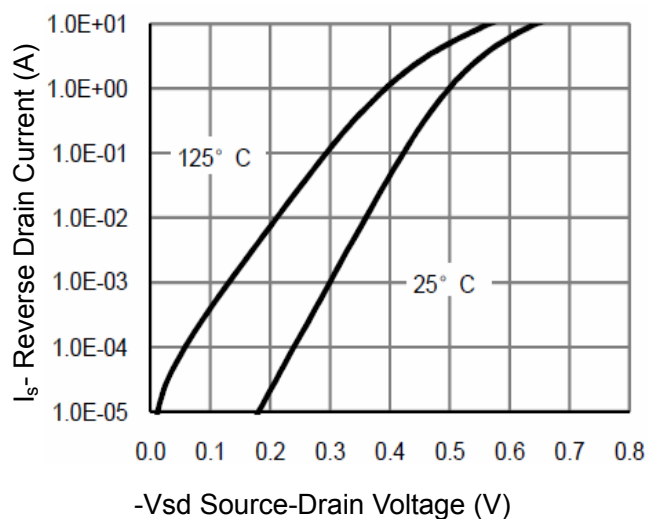
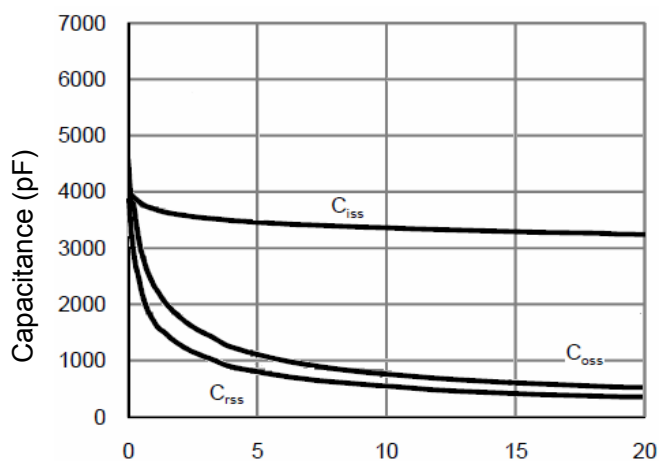
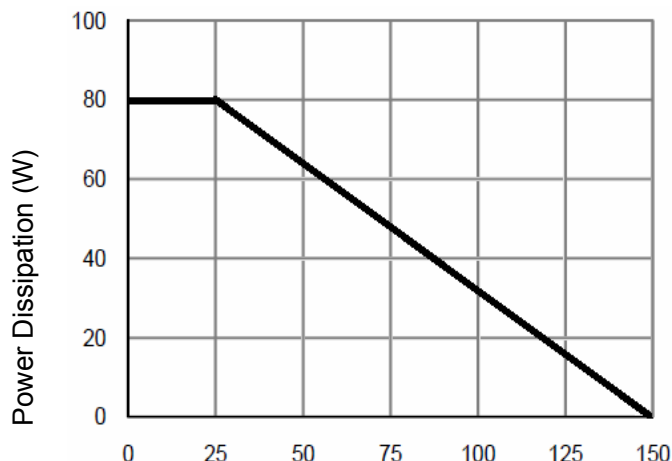


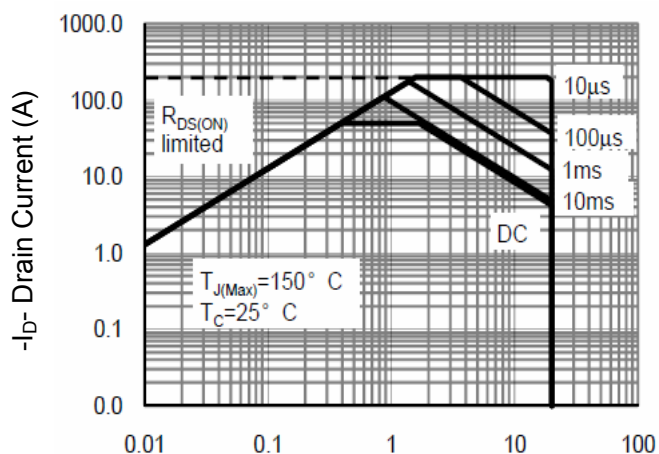
Figure 6 Source- Drain Diode Forward



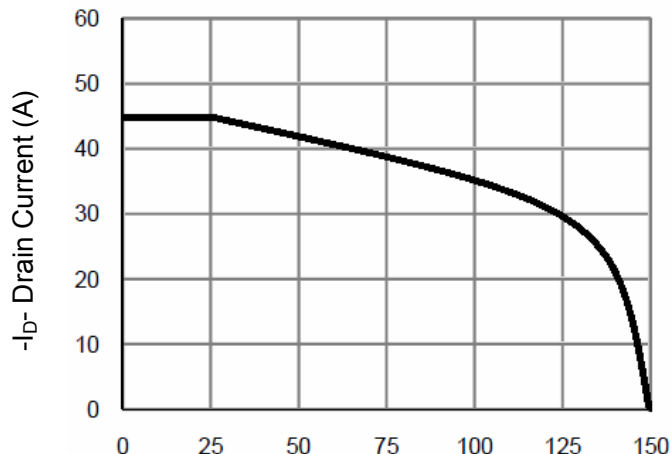
-Vds Drain-Source Voltage (V)
Figure 7 Capacitance vs Vds



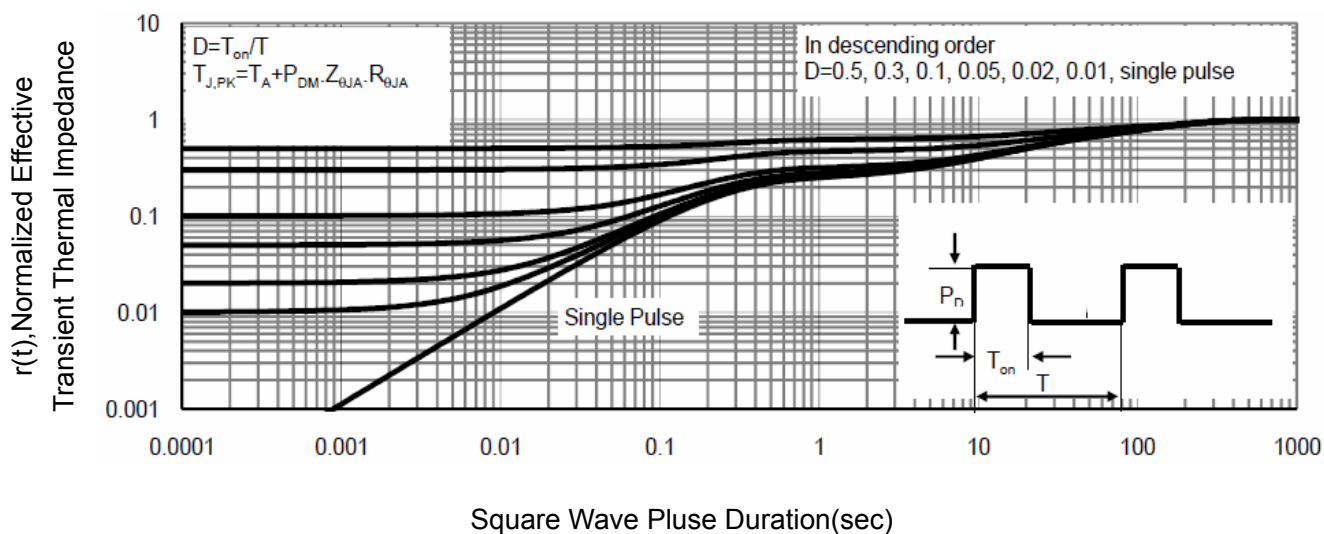
T_J -Junction Temperature(°C)
Figure 9 Power De-rating



-Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area

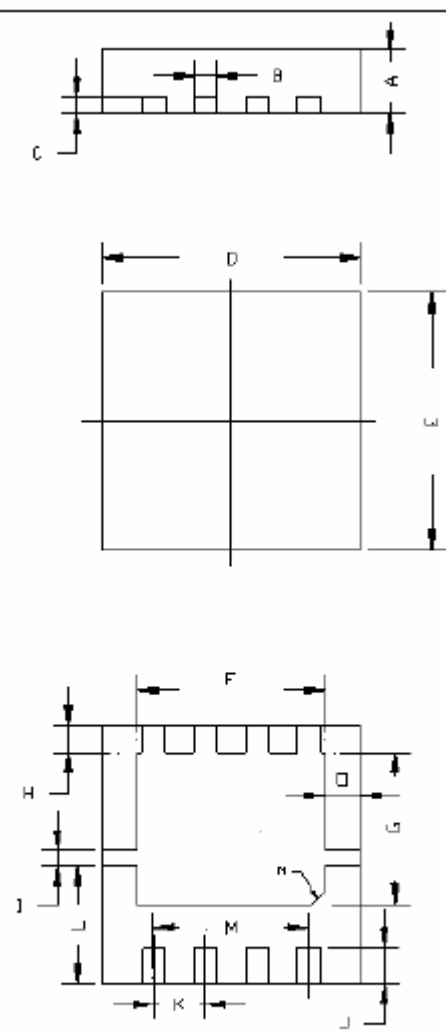


T_J -Junction Temperature(°C)
Figure 10 -Current De-rating



Square Wave Pulse Duration(sec)
Figure 11 Normalized Maximum Transient Thermal Impedance

DFN3.3X3.3 EP Package Information

封装外形尺寸图				
	符号	单位: mm		
		MIN	MAX	TYP
	A	0.75	0.85	0.8
	B	0.25	0.35	0.3
	C	0.18	0.22	0.2
	D	3.2	3.3	3.25
	E	3.2	3.3	3.25
	F	2.2	2.5	2.35
	G	1.8	2.0	1.9
	H	0.3	0.4	0.35
	I	0.15	0.25	0.2
	J	0.4	0.5	0.45
	K	0.6	0.7	0.65
	L	1.38	1.58	1.48
	M	1.8	2.1	1.95
	N	0.15*45°		
	O	0.4	0.5	0.45